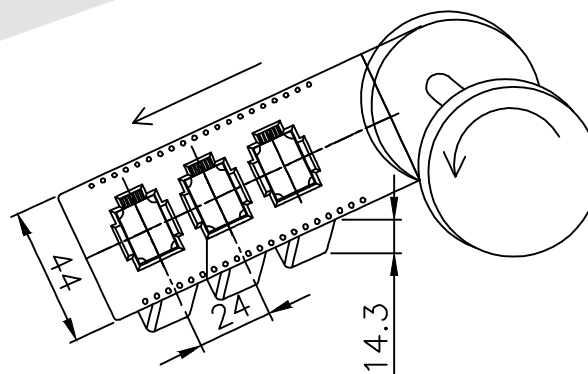
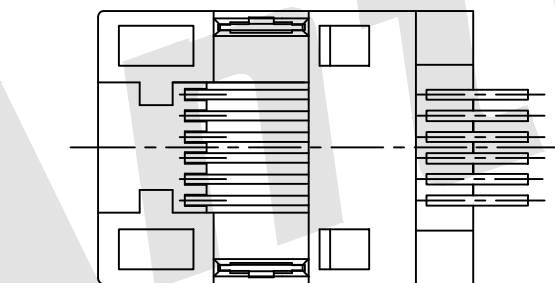
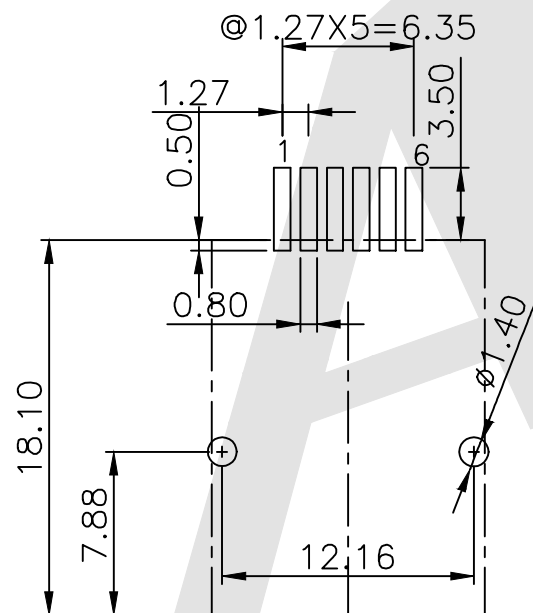
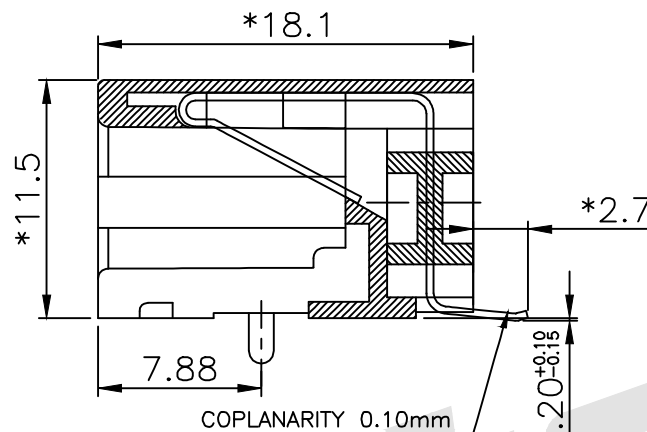
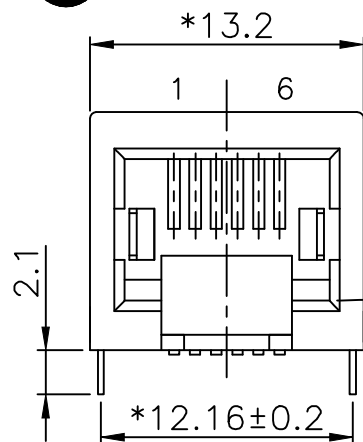


HSF



ROHS



MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER
UL94V-0.2. CONTACT MATERIAL :PHOSPHOR BRONZE $t=0.35\text{mm}$

3. PLATING :SELECTING GOLD PLATING

1u~50u"OVER NICKEL IN CONTACT AREA. 150u" TIN

PLATING

OVER NICKEL IN SOLDER AREA.

4. SHIELD :0.25mm THICKNESS COPPER ALLY WITH
NICKEL .PLATEL

ELECTRICAL:

1. VOLTAGE PATING :125 VAC RMS.

2. CURRENT PATING :1.5 AMP

3. CONTACT RESISTANCE :35 MILLIOHMS MAX

4. INSULATION RESISTANCE:1000 MEGOHMS MIN @
500V DC.5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC
RMS 60Hz. 1MIN

MECHANICAL:

1. DURRABILITY :750 CYCLES MIN

2. PCB RETENTION PRE-SOLDER :10LB MIN

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C .

2. OPERATION : -40°C TO +85°C .

3. IR REFLOW SOLDERING

TEMPERRATURE:255~265°C (5~10 SECONDS) MATES WITH
MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5826B - 6P - 6C - X - A - X

① ② ③ ④ ⑤ ⑥

① SERIES NO:

② NUMBER OF POSITIONS (8P, 6P, 4P)

③ NUMBER OF CONTACTS (8C, 6C, 4C)

④ Contact Plating

G0:Gold flash

G1: 3U" Gold

G2: 5U" Gold

G3:10U" Gold

G4:15U" Gold

G5:30U" Gold

SN:Tin

⑤ Shield

A:W/O Shield

B:Half Shield

C:Shield W/Eml

D:Shield W/O Eml

⑥ packing:

A: Tray packing

R: Tape & Reel

Unless Otherwise specified tolerance

X. ± 0.35 X.XX: ± 0.20 X.X: ± 0.25 X.XXX: ± 0.15

SCALE: UNIT:

As Shown mm

DRAW DATE

Wu Feng Rong 22/03/2018

CHECK DATE

BobYang 22/03/2018



ANTENK ELECTRONICS CO.,LTD

Http://www.antenk.com

E-mail:sales@antenk.com

TITLE:

SIDE ENTRY SMT JACK 6P

DRAWING NO:

ATRJ5826B-6P6C-X-A-X

PRODUCT NO:

ATRJ5826B-6P6C-X-A-X

REV

DESCRIPTION

DATE

1

2

3

4

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6

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